# DATA SHEET 数据表

BONSDA CODE 邦斯达代码	BSD-102
DESCRIPTION 描述	DIP SWITCH_BOX TYPE
<b>CUSTOMER APP</b> 客户确认	PROVAL
PART NO. 料号	:
SIGNATURES <sup>签章</sup>	:

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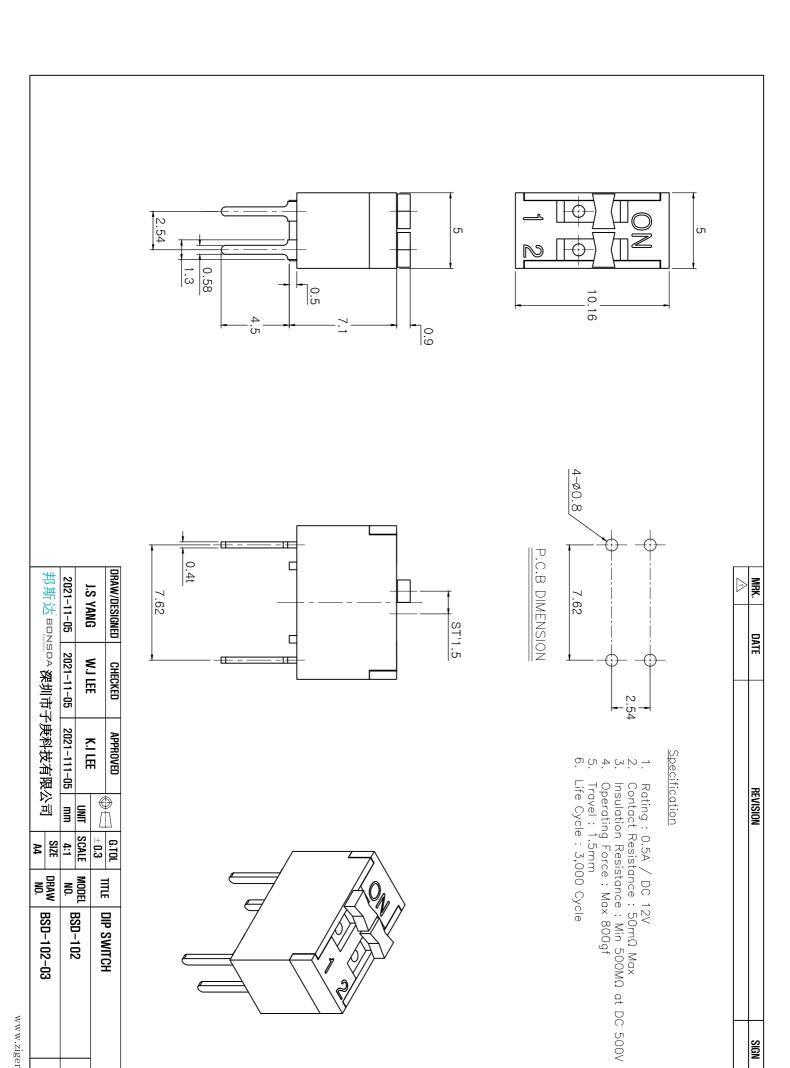
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# DIP SWITCH SPECIFICATION

# **BSD SERIES**

Rev. 02

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# 1. Description:

This specification describes "BOX TYPE DIP SWITCHES", mainly used as signal switch of electric devices, with the general requirements of mechanical and electrical characteristics.

1-1 Operating / Storage Temperature Range: -40°C ~ +85°C

## 2. Rating:

2-1 Non-Switching: 0.5A, 12V

2-1 Switching: 0.3A, 24V

3. Type of Actuation : Actuated by sliding

#### 4. Electrical Characteristics

ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
4-1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product.
4-2	Contact Resistance	<ol> <li>To be measured between the two terminals associated with each switch pole.</li> <li>Measurements shall be made with a 1kHz shall current contact resistance meter.</li> </ol>	50mΩ max. (initial)
4-3	Insulation Resistance	500V DC, 1minute ±5seconds	500 MΩ min.
4-4	Dielectric withstanding Voltage	500V AC(50Hz or 60Hz)shall be applied between all the adjacent terminal and between the terminal and the frame for 1 minute.	There shall be no breakdown or flashover.



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## **5. Mechanical Characteristics**

ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
5-1	Operation Force	Applied in the direction of operation.  ON→OFF  OFF→ON	1000 gf max.
5-2	Stop Strength	A static load of 1 kgf is applied in the operating direction and pulling direction operated for a period of 15 seconds.	There shall be no sign of damage mechanically.
5-3	Soldering Heat Resistance	<ol> <li>Soldering Temperature : See page 4/4</li> <li>Duration of Solder Immersion:         <ul> <li>5±1seconds.</li> </ul> </li> <li>Frequency of Solder Process:         <ul> <li>times max.</li> <li>(PCB is 1.6mm in thickness.)</li> </ul> </li> </ol>	As shown in item 4-2, 4-3, 4-4, 5-1
5-4	Operation Life	Measurements shall be made following the test set forth below:  1) 500mA, 12V DC resistive load  2) Rate of operation: 15~20 cycles/ min  3) Cycle of operation: 3,000 cycles	1)As shown in item 4-3, 4-4 2)Contact Resistance: 500mΩ max (final-after test)

## 6. Environmental Characteristics

ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
6-1	Moisture Resistance	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for one hour before measurements. Are made:  1) Temperature: 40±2°C  2) Relative humidity: 90 to 95% R.H  3) Time: 96 hours  Water drops shall be removed.	1)As shown in item 4-4, 5-1 2)Contact resistance: 50mΩ Max. 3)Insulation resistance: 10MΩ Min.



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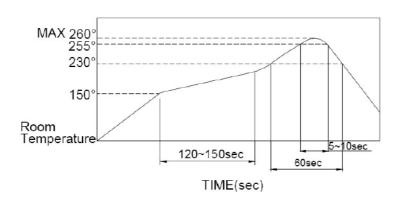
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ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
6-2	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made:  1)Temperature: -40°C ± 3°C  2)Time: 96 hours  Water drops shall be removed.	As shown in item 4-2, 4-3, 4-4, 5-1
6-3	Resistance High Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made:  1)Temperature: 85°C ± 2°C  2)Time: 96 hours	1)As shown in item 4-2, 4-3, 4-4, 5-1

# 7. This item is "RoHS" Compliant

# 8. Soldering Conditions



8-1 The condition mentioned above is the temperature on the Cu foil of the P.C.B surface.

There are cases where board's temperature greatly differs from switch's surface temperature depending on board's material, size, thickness, etc.

Care, therefore, should be used not to allow switch's surface temperature to exceed 260°C.



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